

**MAINTENANCE MANUAL
RADIO
FRONT ASSEMBLY
19D902177G5 (2 CHANNELS)
19D902177G6 (8 CHANNELS)**

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DESCRIPTION

The Front Radio Assembly (19D902177) for the PCS™ Personal Synthesized Radio consists of the following:

- Front Cap Assembly 19D902180G1
- Audio/Logic Board 19D902142G3/G4
- Metal Over Elastomer (MOE) Connector 19A705662P1 and Holder 19B801570P2

The Front Cap Assembly consists of a LEXAN front housing, a control assembly and a speaker. The control assembly houses all operator switches, Liquid Crystal Display (LCD) and microphone. The Metal Over Elastomer Connector interfaces the printed runs on the control assembly to the printed runs on the audio/logic board.

FRONT CAP ASSEMBLY

Front Cap Assembly 19D902180G1, for the Ericsson GE PCS™ Personal Radio, consists of a molded plastic circuit board (Control Frame), a Liquid Crystal Display (LCD) assembly, switches for the basic radio functions and a User Device Connector (UDC) all mounted in a plastic front housing. The Assembly Diagram listed in the Table of Contents shows two views: a pictorial view of the Control Assembly and a view of the Control Assembly mounted into the radio front housing. The Control Frame acts like a three dimensional printed circuit board. The base material is "ULTEM" which is a molded plastic with a two layer printed circuit pattern on the outside perimeter of the frame. This structure interfaces several electrical components as follows:

- Control Switches
- Liquid Crystal Display (LCD)
- Microphone

- Speaker
- User Device Connector (UDC)

AUDIO/LOGIC BOARD

Audio/Logic Board 19D902142 mounts in Front Cap Assembly 19D902180G1 as shown in Figure 1. All Front Cap switch operations are connected to the audio/logic board through the MOE interface connector. A microprocessor on the audio/logic board interprets these commands and issues commands to the audio/logic circuits, the RF circuits and the LCD module on the control assembly. The MOE is again the transmission path between assemblies. The microphone and speaker audio is also transferred through the MOE path (Refer to Figure 2 for a block diagram of the microprocessor and associated circuitry and Figure 3 for a block diagram of the audio paths).

The audio/logic board consists primarily of the following:

- Microprocessor
- EEPROM
- RX Audio Processing
- TX Audio Processing
- Regulators and Special Circuits

CIRCUIT ANALYSIS

FRONT CAP ASSEMBLY

Control Switches

A "Dome" switch pad adheres to the control frame. These switches are domed metal switches which makes direct contact F with runs on the control frame. The switches include the PTT, R monitor, channel up, volume up and volume down controls. O Refer to the Schematic Diagram listed in the Table of Contents N for switch operation. A rubber keypad fits over the switch T assembly for operator interface and weather protection.

LCD Assembly

The LCD (Liquid Crystal Display) assembly consists of S LCD driver board A1, a diffuser, two zebra strips, the LCD and E a lens. This assembly is held together by the lens. The primary M function of this board is to light LCD segments as controlled B by the radio microprocessor located on the audio/logic board. Another function of this board is to provide backlighting of the L LCD module. This is accomplished by using four LED devices Y (D1 - D4). These LED's are turned on by LCD DAT/LT line and powered by a voltage switching circuit consisting of chip transistors Q1 and Q2. The diffuser placed immediately above the LED's evenly distributes the light. The zebra strips connect

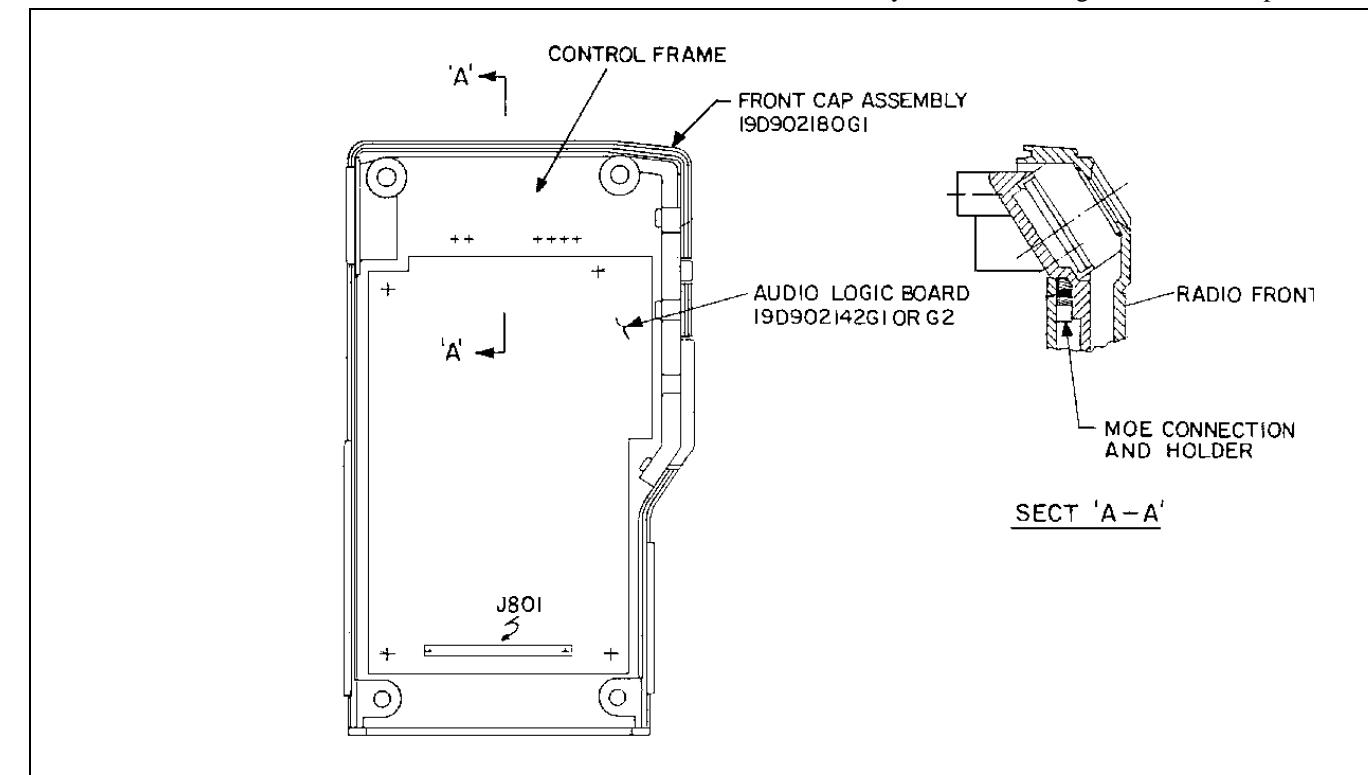


Figure 1 - Radio Front Assembly

the driver board to the LCD. This entire assembly is soldered to the control frame through six pins.

Microphone And Speaker

The microphone (B901) mounts directly onto the control frame (HL1 and HL2). The control assembly, when placed into the Radio Front Assembly, is located in the correct position for receiving voice when used. The speaker, mounted in the front housing, connects to the control frame (HL3 and HL4) through two wires. A protective grill cloth is placed over the front housing before the speaker is mounted to provide weather-proofing.

User Device Connector (UDC)

Part of the control frame forms UDC connector U901 for customer programming and for connecting external options. The speaker leads, mic high and PTT are all brought to this connector along with ground. The mic lead and one of the speaker leads are switched to the UDC only when microswitches S1 and S2 are operated. These switches are activated by plungers on compatible PCS Personal Radio options. A rubber boot is placed over this connector for weather protection

AUDIO/LOGIC BOARD

Microprocessor (80C51)

An 8-bit microprocessor is used to provide all of the control signals required by the radio. The microprocessor also generates Channel Guard tones and detects Channel Guard and Type 99 tones.

The microprocessor (U1) is located on Spur Filter Board A701. This board consist of RC filters on each port of the processor and a metal can soldered on top of the board to reduce the effect of microprocessor-generated spurious signals.

Microprocessor Port/Pin Definitions

Port Pins
I=Input
O=Output
I/O=Bidirectional

P0.0 (O)	Channel Guard encode bit 0/Volume attenuator bit 0
P0.1 (O)	CG encode bit 1/Volume attenuator bit 1
P0.2 (O)	CG encode bit 2/Volume attenuator bit 2

P0.3 (O) CG encode bit 3/Voice mute
P0.4 (I) Low Battery indication (active low)

P0.5 (O) Transmit CG switch (active high)
P0.6 (O) Delayed PTT (active high)
P0.7 (O) Mute (active low)
P1.0 (I) Monitor (active low)
P1.1 (I) Vol Up (active low)

P1.2 (I) Vol Dn (active low)
P1.3 (I) Ch Up (active low)
P1.4 (I) CAS (active low)
P1.5 (O) Xtal switch (active high)
P1.6 (O) Mic mute (active low)
P1.7 (O) Power select
P2.0 (O) LCD enable

P2.1 (O) LCD data
P2.2 (O) LCD clock
P2.3 (O) Receive mute (active high)
P2.4 (O) Type 99 enable (active high)

P2.5 (O) Synthesizer clock
P2.6 (O) Synthesizer data
P2.7 (O) Synthesizer enable

RXD (I) Programmer data in
TXD (O) Programmer data out
P3.2 (I) Tone data in
P3.3 (I) Lock detect (active high)
P3.4 (O) Alert tone
P3.5 (O) EEPROM power enable
P3.6 (O) EEPROM clock

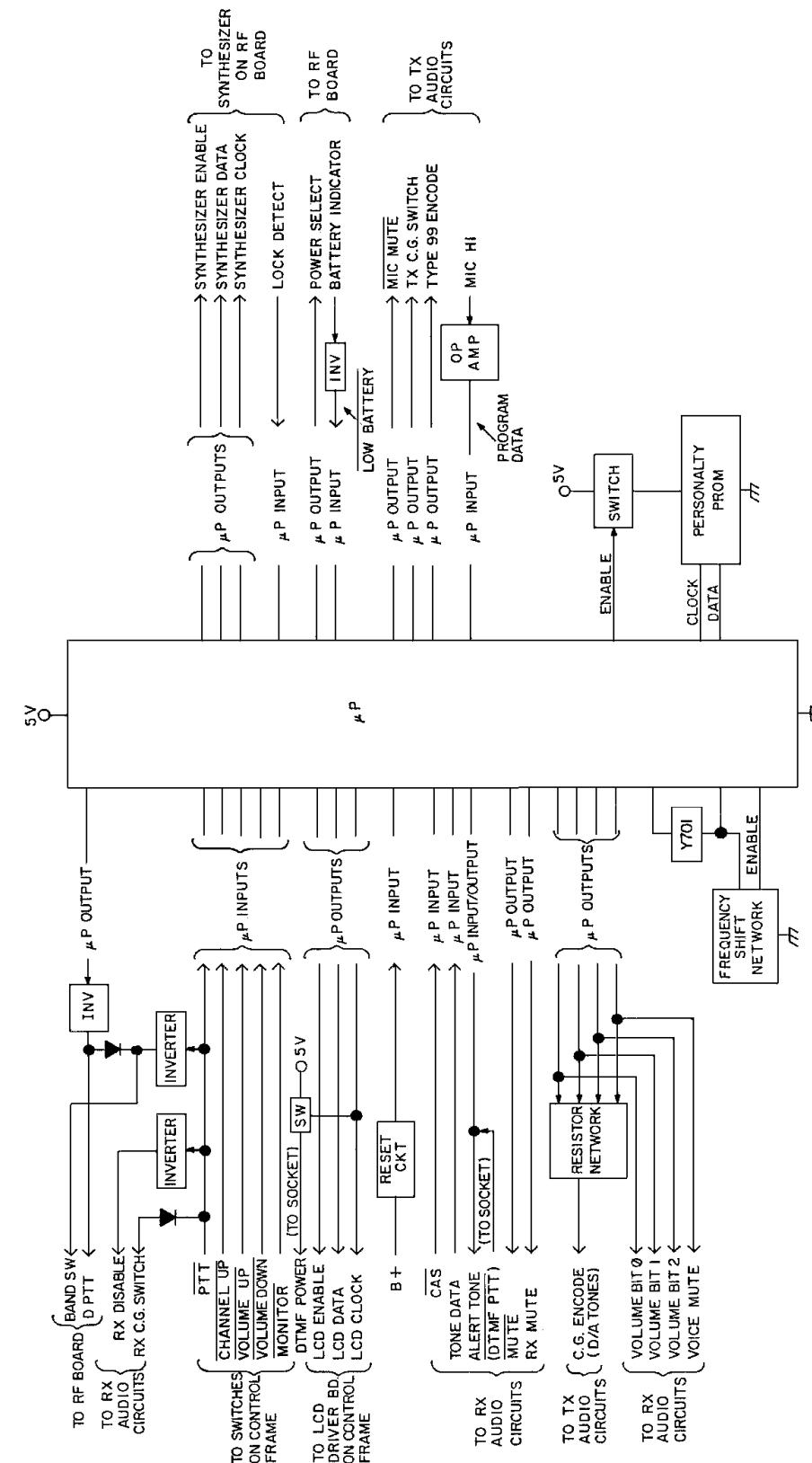
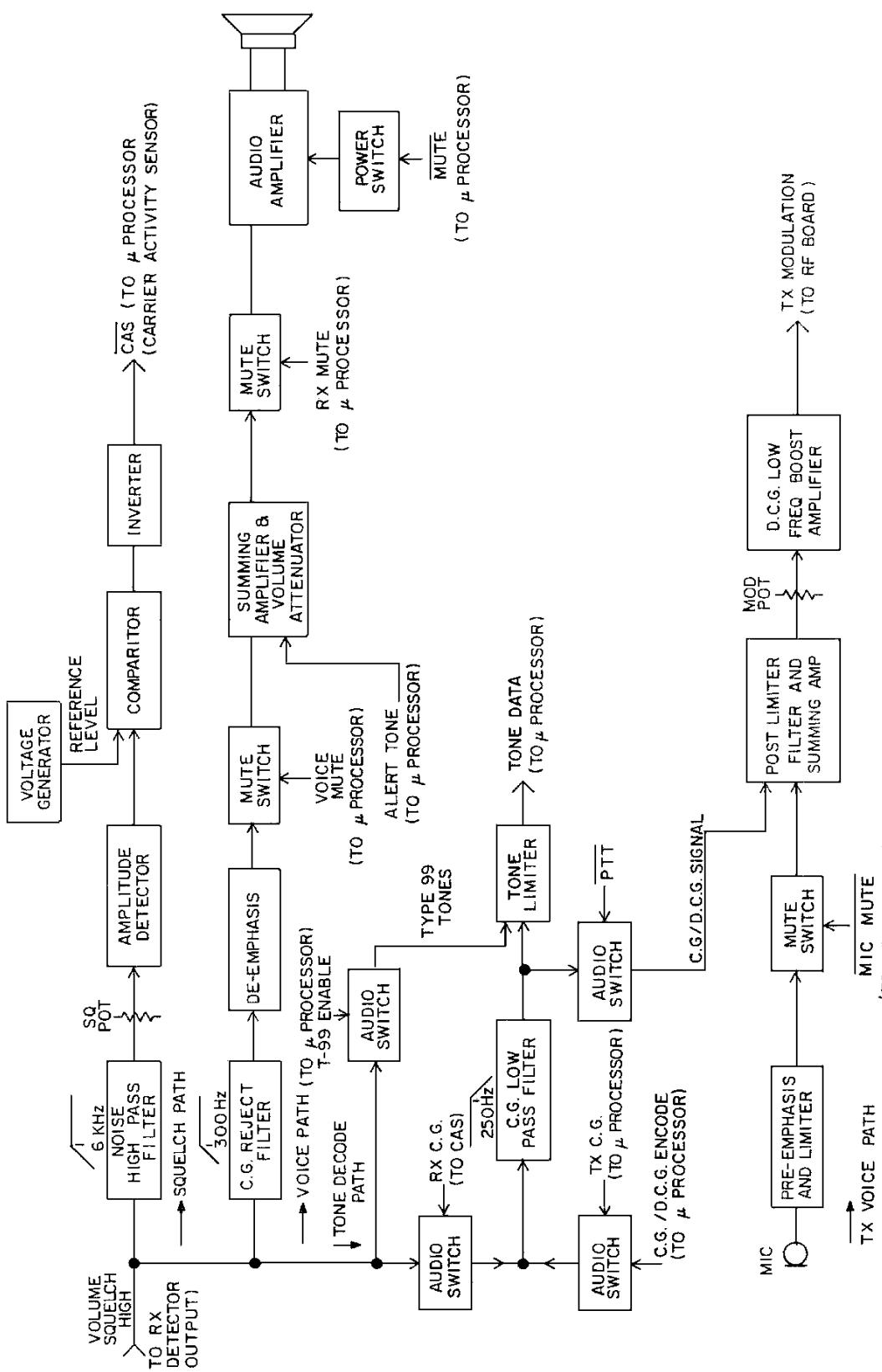


Figure 2 - Microprocessor Block Diagram



P3.7 (I/O) EEPROM data

EEPROM

The 512 x 8 - bit EEPROM (U701), commonly referred to as the personality PROM, stores customer information as follows:

- Customer frequencies
- Customer tones
- Customer Options

Using this EEPROM provides the convenience of programming without opening the radio.

Programming of the EEPROM is accomplished by driving the **MIC HI** lead. This lead is connected to operational amplifier circuit U302-B. With no external signal connected to **MIC HI**, a voltage level of approximately 2.25 volts is at **MIC HI**. This causes the output of U302-B, the program data line, to be high. If the **MIC HI** is pulled low, the program data line is pulled low. If this line remains low for 20 milliseconds or greater, the microprocessor is put in the programming mode. Once in this mode, the radio will not operate or respond to any front case button. The radio must be turned off and then back on to get the processor out of this mode. If programming is actually done, the processor will be taken out of the programming mode by the proper character from the personal computer programmer.

RX Audio Processing

Voice Path

Received audio enters the audio/logic board at J801, Pin 10. Frequencies below 300 Hz are attenuated by the Channel Guard reject filter consisting of U602A and associated circuitry.

The output from the CG reject filter is coupled through voice mute switch transistor Q603 to the volume attenuator circuit U602B and resistors R632 through R640. Here the 500 Hz alert tone, generated by the microprocessor, can be added to the received audio. The volume attenuator has a range of 48 dB. The attenuator output is coupled through **RX MUTE** switching transistor Q606 to audio amplifier transistor U604. Power is supplied to the audio amplifier by transistor Q605 and controlled by the **MUTE** line from the microprocessor. Amplifier U604 drives the speaker with differential outputs, which are also connected to the accessory connector through the Control Assembly.

A 6 dB/octave de-emphasis is provided by capacitor C615 and resistor R628 in the CG reject filter. Capacitor C622 and resistor R645 provide additional roll-off at higher frequencies.

Squelch Path

The squelch circuit operates on the noise components contained in the discriminator output. The signal at J801, Pin 10 is applied to a high-pass filter consisting of U601B and associated **F** circuitry. The output of U601B is noise in a band around 6 kHz. **R**
O
N

The output of U601B is rectified by U601A, resistors R610 **T** through R612 and capacitors C607 and C608. This d.c. signal is then input to comparator U601D. If the rectified noise is more than approximately 0.20 Vd.c., the **CAS** line is high and the **A** microprocessor mutes the audio. Resistors R613 and R615 **S** provide about 2 dB of hysteresis. Resistors R614, R662, R663 **S** and thermister R664 are used for temperature compensation or **E** the threshold level. **M**

The threshold level is temperature compensated at cold **B** temperatures only. This is necessary because of a drop in the **L** **VOL/SQ. HI** noise level. Thermister R664 has a negative **Y** temperature coefficient. At 25 C and above, the thermister has little effect on the threshold voltage level at U601B, Pin 12. At temperatures below 25 C, the resistance increased exponentially, thereby causing a drop in the threshold voltage. This voltage drop approximately tracks the voltage drop at the detected noise terminal, U601B, Pin 13.

Limited Tone Data Path

Limited Tone Data is the 5 Volts (peak-peak) representation of a received tone and is fed to the microprocessor where the actual tone decoding occurs. This circuit consists of a low-pass filter for voice rejection and a voltage comparator.

The low-pass filter consists of U606A and associated circuitry. This filter is used for both Channel Guard encoding and decoding. The filter has a breakpoint at 210 Hz. Type 99 decoding is done by bypassing the low-pass filter and going directly to comparator U606B.

Tx Audio Processing

Audio from the microphone is applied to a 6 dB/octave pre-emphasis network consisting of capacitor C301 and resistor R306 and then to amplifier-limiter U301A. The output of U301A is coupled through mic mute switch U605C to the post-limiter filter consisting of U302A and associated circuitry. Transmit Channel Guard tones are added to the microphone audio at the post-limiter filter.

The transmit signal is applied to the low-frequency boost circuit U303A, U303B and associated circuitry. The transmit deviation is set by MOD potentiometer R321.

The low frequency boost circuitry provides an increasing output level as the input frequency decreases below 20 Hz. The shape of the response curve is shown in Figure 4. This shape is intended to be the mirror image of the synthesizer frequency response curve. The combined result of these two curves provide relatively flat modulation below 5 Hz. This is necessary for Digital Channel Guard modulation.

Regulator And Special Circuitry

+5 Volt Regulator

A +5 volt regulator (U802) supplies power to the microprocessor and all other circuitry requiring +5 volts. A voltage divider provides the input to U601-C to generate a 2.25 volt reference for operational amplifier biasing.

Low Voltage Reset

Voltage detector U801 along with transistor Q803 provides the microprocessor with the necessary reset signal during the power up routine and also resets the microprocessor when the battery falls below approximately 4.75 volts (Refer to Figure 5).

Low Battery Indicator

When the battery voltage drops to approximately 6.3 volts, the **BATT IND** line from the RF board is sufficiently high to turn on transistor Q802. The output of Q802, the low battery line, drives a microprocessor port. This action turns on the **BAT** pixel on the LCD.

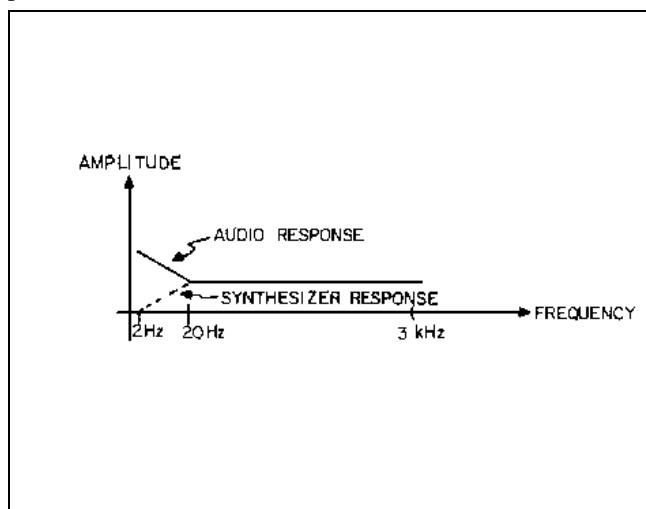


Figure 4 - Audio Response Curve

User Input

Control assembly connector J901, located on the audio/logic board, provides an interface between the user and the radio. By pressing buttons on the switch panel, the user may change the volume level or channel, monitor a channel, or key the transmitter. The LCD is updated to reflect the current status of the radio. The microprocessor configures the LCD through **LCD EN** (P2.0), **LCD DAT** (P2.1) and **LCD CLK** (P2.2).

Synthesizer Programming

After a reset, when toggling between transmit and receive, and any time a new channel is selected, the microprocessor must reprogram the synthesizer through **SYN CLK** (P2.5), **SYN DAT** (P2.6) and **SYN EN** (P2.7). When locked, the **LOCK DET** line (J9801-11) is high.

Alert Tone

The microprocessor generates a 500 Hz alert tone (P3.4) used to signal the user of critical events. These events include synthesizer out of lock and activation of the volume up, volume down and channel up buttons. The alert tone can be disabled by the programmer.

Microprocessor Xtal Frequency Pull

Port P1.5 of the microprocessor is used to switch a 33 pF capacitor (C701) into the crystal oscillator circuit. The effect of adding this capacitor is to move or pull the xtal frequency approximately 250 ppm. This is done to keep harmonics of the microprocessor **ALE** line away from the receive channel frequency.

The programming from this point happens automatically when channel frequencies are initially programmed.

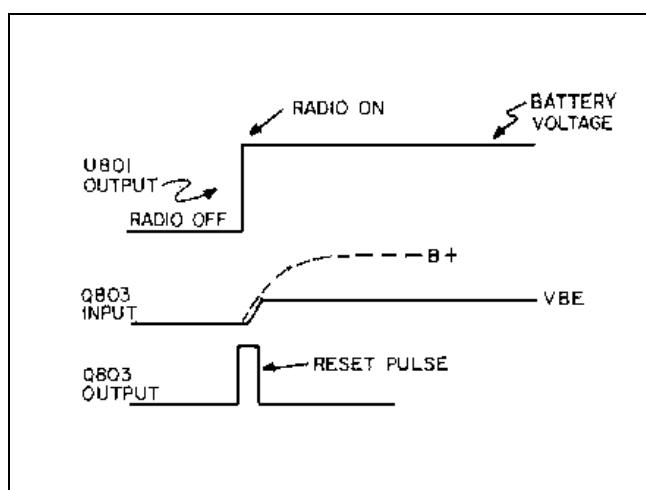


Figure 5 - Voltage Waveforms

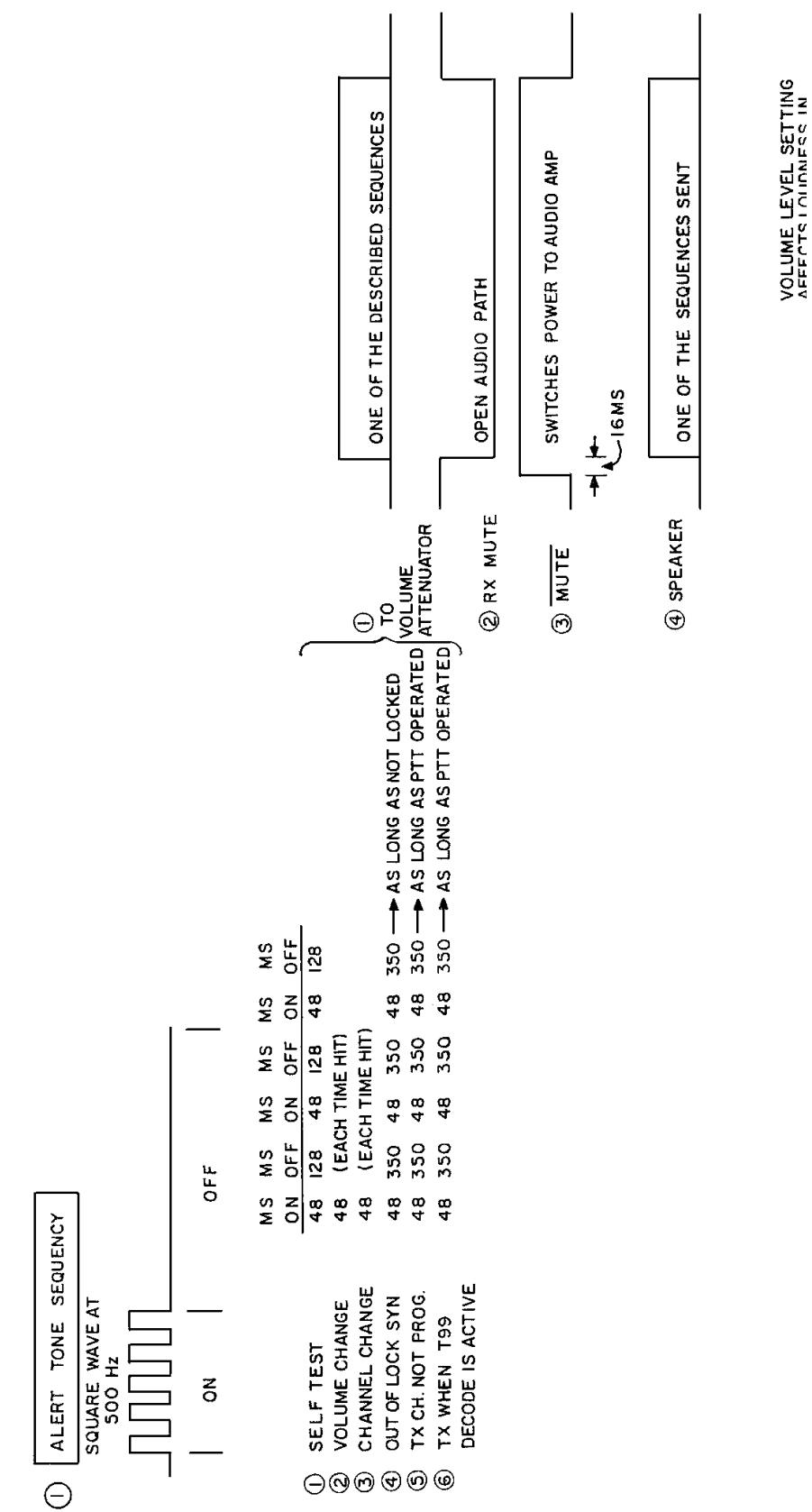
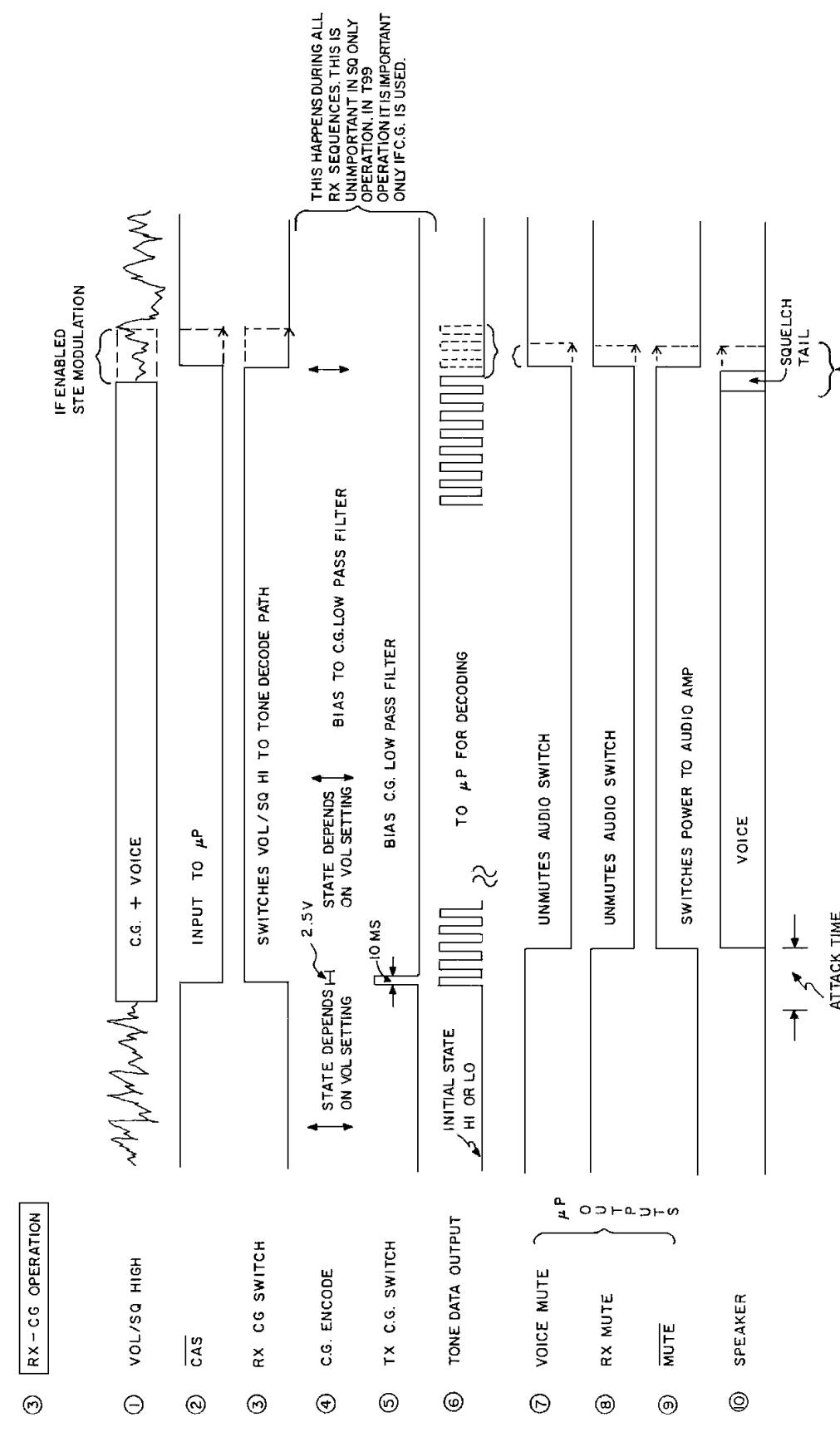
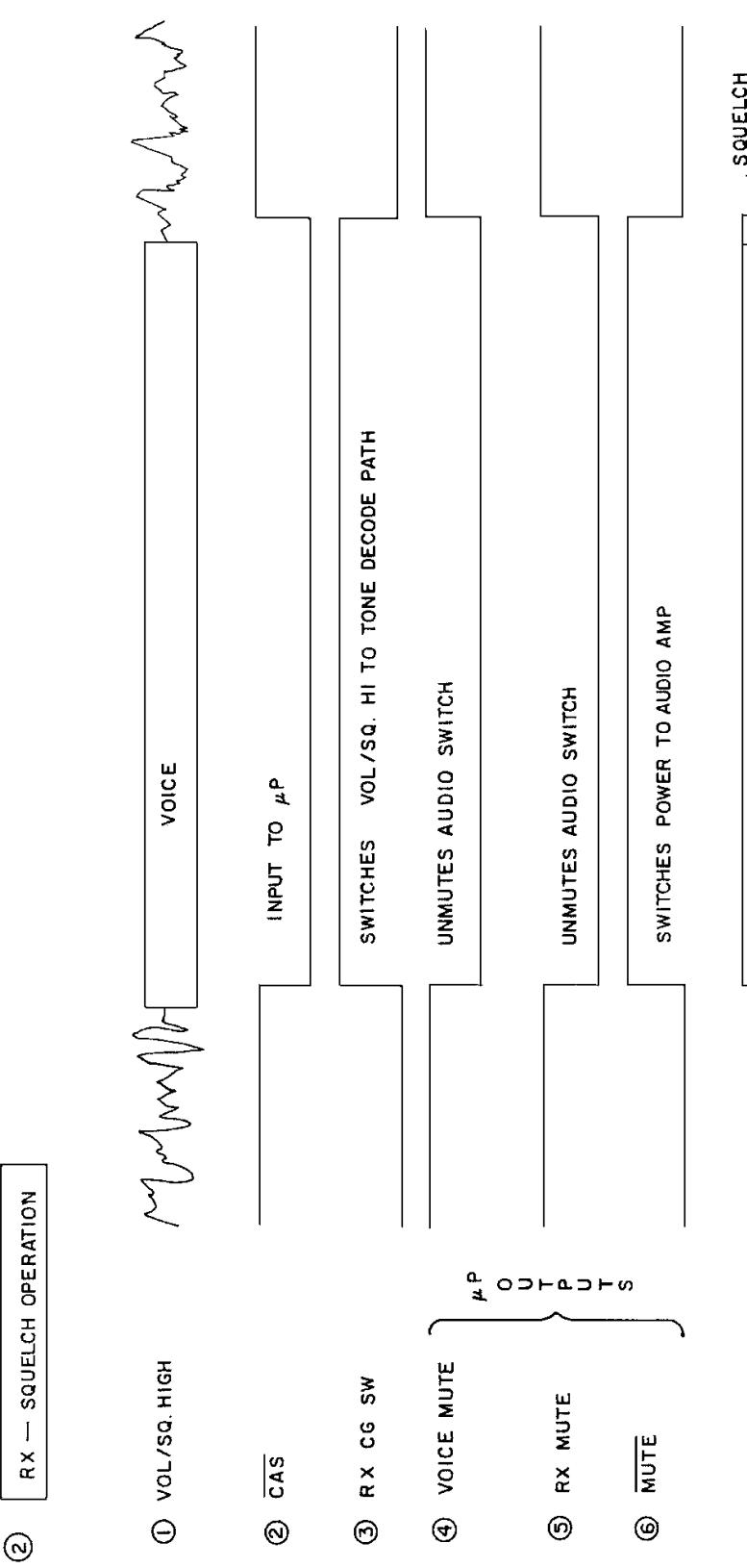


Figure 6 - Alert Tone Sequences



F R O N T A S S E M B L Y

④ RX - TYPE 99 OPERATION

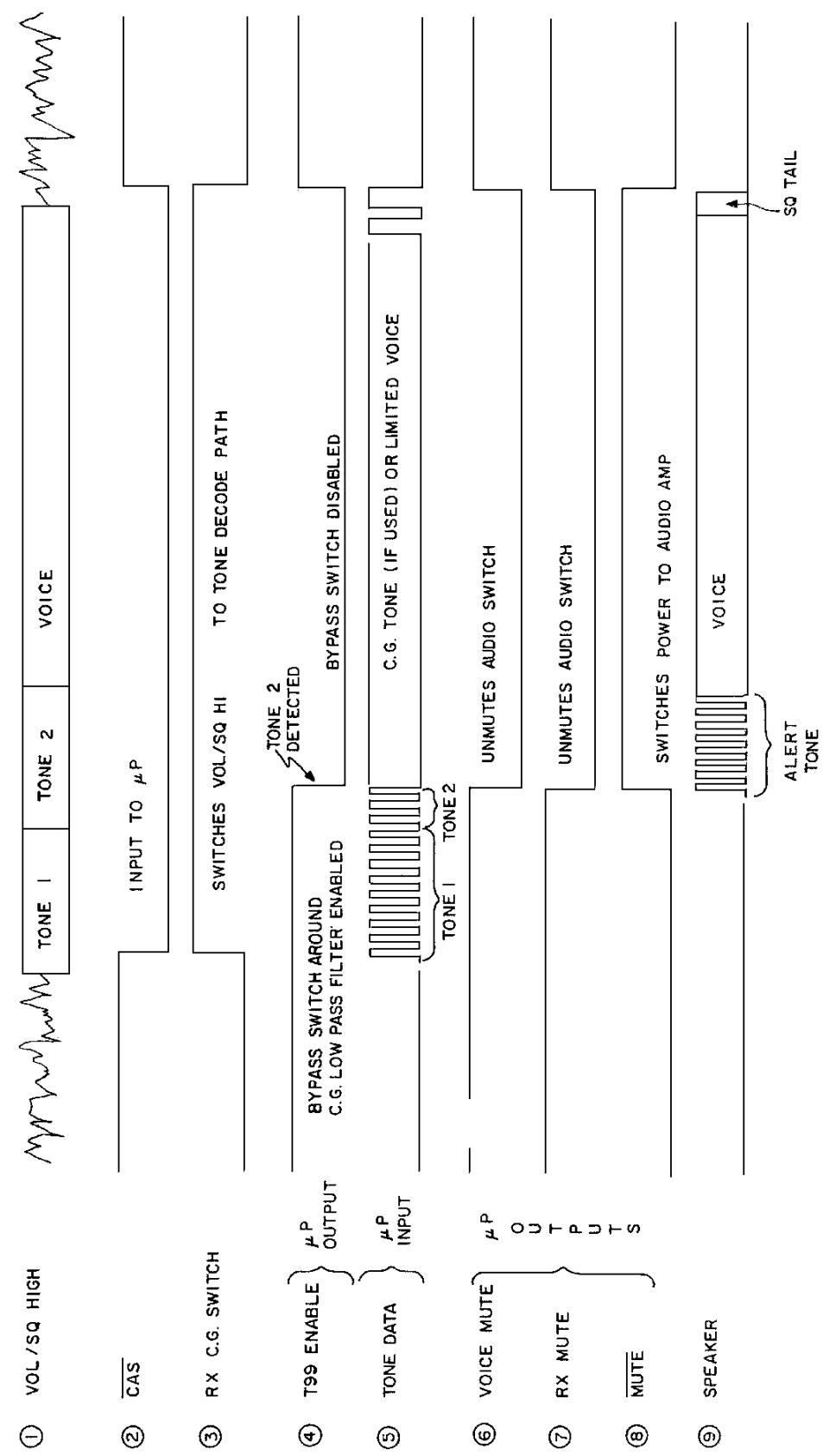


Figure 9 - RX Type 99 Operation

⑤ TX-VOICE ONLY

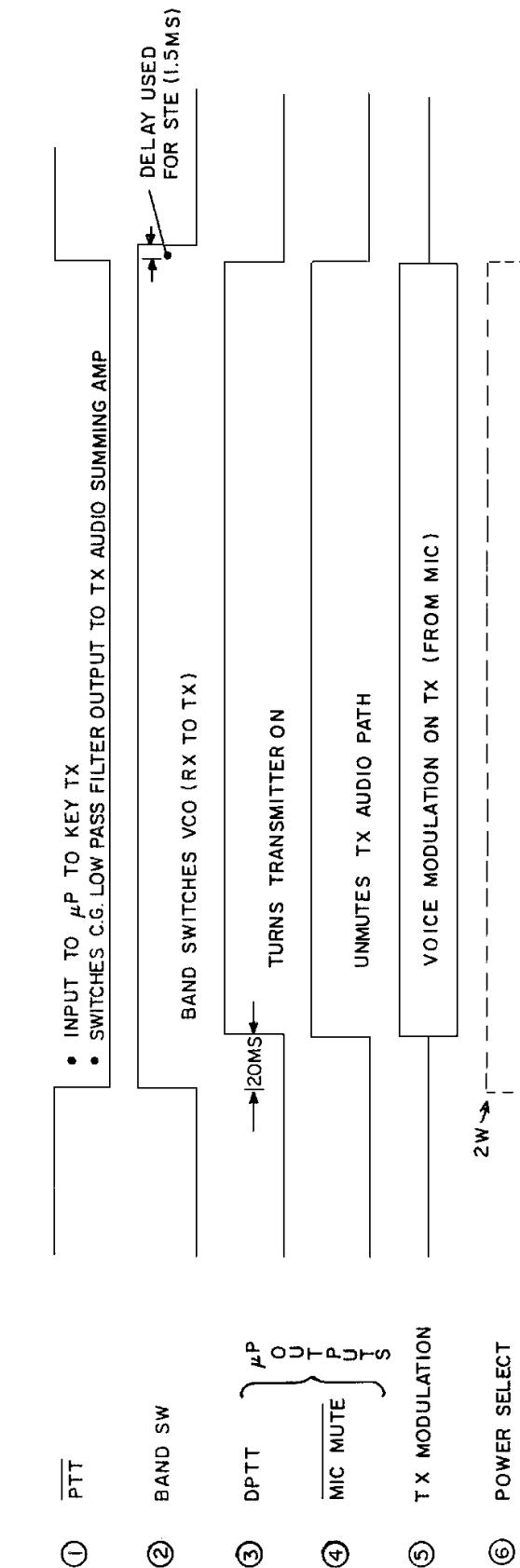


Figure 10 - TX Voice Only Operation

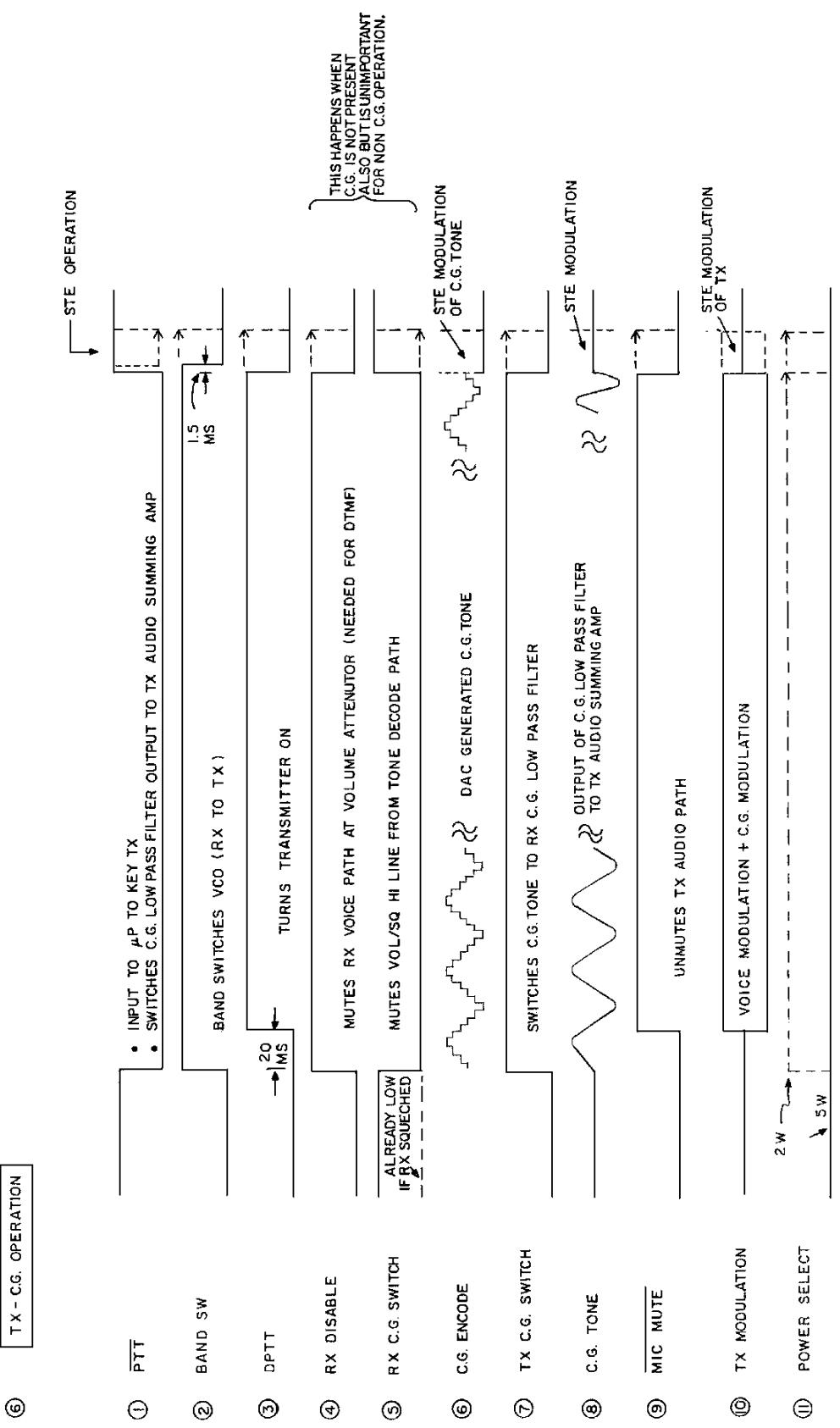


Figure 11 - TX Channel Guard Operation

RADIO FRONT ASSEMBLY
19D902177G5 (2 Channels)
19D902177G6 (8 Channels)
Issue 3

SYMBOL	PART NO.	DESCRIPTION
A2		AUDIO/LOGIC BOARD 19D902142G3 (Used in G5) 19D902142G4 (Used in G6)
A701		MICROPROCESSOR/SPUR FILTER BOARD 19C851678G1 (Used in G3) 19C851678G2 (Used in G4)
		----- CAPACITORS -----
C1 thru C34	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.
C35	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
C36	19A702061P35	Ceramic: 30 pF ±5%, 50 VDCW, temp coef 0±30 PPM.
		----- PLUGS -----
P701	19B801573P1	Connector.
		----- RESISTORS -----
R1	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R2 and R3	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R4 and R5	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R6	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R7 thru R14	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R15 thru R17	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R18 thru R22	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R23 thru R25	19B801251P471	Metal film: 470 ohms ±5%, 1/10 w.
R26 thru R30	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R31 thru R34	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.
R35	19B801251P220	Metal film: 22 ohms ±5%, 1/10 w.
		----- INTEGRATED CIRCUITS -----
U1	19A705557P8	Microcomputer; sim to INTEL N80C52. (Used in G1).
U1	19A705557P9	Microcomputer; sim to INTEL N80C52. (Used in G2).
		----- CAPACITORS -----
C301	19A702052P7	Ceramic: 2200 pF ±10%, 50 VDCW.
C302	19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.
C303	19A702061P61	Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0±30 PPM.
C304	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
C305	19A702052P110	Ceramic: 4700 pF ±5%, 50 VDCW.
C306	19A705205P2	Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.
C307	19A702052P107	Ceramic: 2200 pF ±5%, 50 VDCW.

*COMPONENTS ADDED, DELETED, OR CHANGED BY PRODUCTION CHANGES

SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION	SYMBOL	PART NO.	DESCRIPTION
C308	19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.	C702	19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.	R316	19B801251P393	Metal film: 39K ohms ±5%, 1/10 w.
C309	19A702061P67	Ceramic: 180 pF ±5%, 50 VDCW, temp coef 0±30 PPM.	C703 and C704	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30 PPM.	R317	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
C310	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	C705	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.	R318	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
C311	19A702052P130	Ceramic: 0.022 μF ±5%, 50 VDCW.	C801	19A705205P2	Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.	R319	19B801251P683	Metal film: 68K ohms ±5%, 1/10 w.
C312 and C313	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	C804	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.	R320	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
C314	19A702061P73	Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.	C805	19A701534P9	Tantalum: 47 μF ±20%, 6.3 VDCW.	R321	19A705496P7	Variable, surface mount: 100K ohms ±25%, 1/10 w.
C315 and C316	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	C806	19A704879P5	Electrolytic: 10 μF ±20%, 16 VDCW.	R322	19B801251P183	Metal film: 18K ohms ±5%, 1/10 w.
C317	19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.	C807	19A705205P14	Tantalum: 6.8 μF, 6 VDCW; sim to Sprague 293D.	R324	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
C318	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	C808	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.	R325	19B801251P823	Metal film: 82K ohms ±5%, 1/10 w.
C601	19A702052P107	Ceramic: 2200 pF ±5%, 50 VDCW.	D601	19A705377P3	Silicon, Hot Carrier: sim to HSMS-2920.	R326	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
C602	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30 PPM.	D701 thru D704	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.	R327	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
C603	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30 PPM.	D705 thru D707	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.	R329	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
C604	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW.	D801	19A116585P1	Silicon, fast recovery, 600 mA, 50 PIV.	R330	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
C605	19A702052P7	Ceramic: 2200 pF ±10%, 50 VDCW.	J701		----- JACKS -----	R601	19B801251P273	Metal film: 27K ohms ±5%, 1/10 w.
C606 and C607	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	J801	19A705482P1	Part of printed wire board.	R602	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
C608	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30 PPM.	J802	19B209648P1	Printed wire board connector.	R603	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
C609	19A702052P130	Ceramic: 0.022 μF ±5%, 50 VDCW.	J901		Contact, electrical.	R604	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.
C610	19A702052P110	Ceramic: 4700 pF ±5%, 50 VDCW.	Q601 and Q602	19A700076P2	Part of printed wire board.	R605	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
C611 and C612	19A702052P114	Ceramic: 0.01 μF ±5%, 50 VDCW.	Q603	19A700059P2	----- JACKS -----	R606	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
C613	19A702052P130	Ceramic: 0.022 μF ±5%, 50 VDCW.	Q604	19A700076P2	Part of printed wire board.	R607	19B801251P681	Metal film: 680 ohms ±5%, 1/10 w.
C614	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	Q605	19A700026P2	----- TRANSISTORS -----	R608	19A705496P6	Variable resistor, surface mount: 50K ohms ±25%, adjustment range 15 to 85%; sim to Murata Type RGV4E.
C615	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.	Q606	19A700059P2	Silicon, NPN: sim to MMBT3904, low profile.	R609 and R610	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
C616	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.	Q607	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.	R611	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
C617	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.	Q608	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.	R612	19B801251P124	Metal film: 120K ohms ±5%, 1/10 w.
C618	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.	Q609	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.	R613	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
C619	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.	Q610	19A700076P2	Silicon, NPN: sim to BC369.	R614	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
C620	19A704879P14	Electrolytic: 68 μF ±20%, 10 VDCW.	Q611	19A700076P2	Silicon, PNP: sim to MMBT3906, low profile.	R615	19B801251P563	Metal film: 56K ohms ±5%, 1/10 w.
C621	19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.	Q612	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.	R616	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
C622	19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.	Q701	19A134739P2	Silicon, NPN.	R617	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
C623	19A704879P5	Electrolytic: 10 μF ±20%, 16 VDCW.	Q702	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.	R618	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
C624	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.	Q704	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.	R619	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
C626 and C627	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.	Q706	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.	R620	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
C628	19A702052P2	Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.	Q801	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.	R621	19B801251P562	Metal film: 5.6K ohms ±5%, 1/10 w.
C629 and C630	19A702052P110	Ceramic: 4700 pF ±5%, 50 VDCW.	Q802 and Q803	19A700076P2	Silicon, PNP: sim to MMBT3904, low profile.	R622	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
C631	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.	R301	19B801251P104	Silicon, PNP: sim to MMBT3906, low profile.	R623	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
C632	19A702052P22	Ceramic: 0.047 μF ±10%, 50 VDCW.	R302	1				

PARTS LIST

LBI-38454

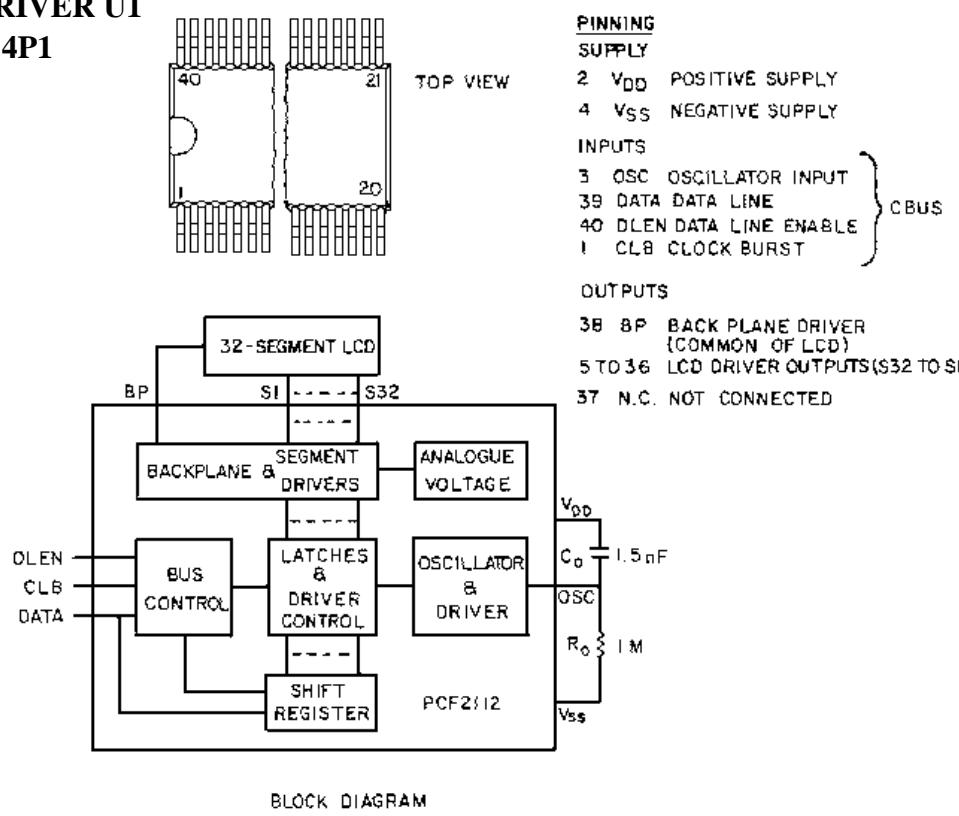
SYMBOL	PART NO.	DESCRIPTION
R650	19B801251P154	Metal film: 150K ohms ±5%, 1/10 w.
R651	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R652 and R653	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R654	19B801251P682	Metal film: 6.8K ohms ±5%, 1/10 w.
R655 and R656	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
R657	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R658	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R659	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R660	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R661	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R662 and R663	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R664	19A705813P1	Thermistor: sim to AL03006-624-73-G100.
R668 and R669	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R670	19B801251P563	Metal film: 56K ohms ±5%, 1/10 w.
R671	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
R672	19B801251P561	Metal film: 560 ohms ±5%, 1/10 w.
R673	19B801251P334	Metal film: 330K ohms ±5%, 1/10 w.
R674	19B801251P684	Metal film: 680K ohms ±5%, 1/10 w.
R675	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
R676	19B801251P394	Metal film: 390K ohms ±5%, 1/10 w.
R677	19B801251P334	Metal film: 330K ohms ±5%, 1/10 w.
R679	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R701 thru R704	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R705	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R706	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R707	19B801251P334	Metal film: 330K ohms ±5%, 1/10 w.
R708 and R709	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R710	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R711	19B801251P334	Metal film: 330K ohms ±5%, 1/10 w.
R712	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R715 thru R720	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R721	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R722	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R723 thru R725	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R726	19B801251P824	Metal film: 820K ohms ±5%, 1/10 w.
R727	19B801251P394	Metal film: 390K ohms ±5%, 1/10 w.
R728	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R729	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R730	19A702931P234	Metal film: 2210 ohms ±1%, 200 VDCW, 1/8 w.
R731	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R732	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R801	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R802	19B801251P183	Metal film: 18K ohms ±5%, 1/10 w.
R803	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
R804 and R805	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R806	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R807	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.

SYMBOL	PART NO.	DESCRIPTION
R808	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R809	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R810	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R811	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
		----- INTEGRATED CIRCUITS -----
U301	19A705450P2	Dual Operational Amplifier, sim to MC34072.
U302 and U303	19A702293P3	Linear: Dual Op Amp; sim to LM358D.
U601	19A702293P1	Linear: Quad Op Amp; sim to LM324D.
U602	19A702293P3	Linear: Dual Op Amp; sim to LM358D.
U603	19A702705P3	Digital: 8-Channel Analog Multiplexer; sim to 4051BM.
U604	19A705452P1	Linear: Audio Amplifier; sim to TDA 2822M.
U605	19A702705P4	Digital: Quad Analog Switch/Multiplexer; sim to 4066BM.
U606	19A702293P3	Linear: Dual Op Amp; sim to LM358D.
U701	19A704724P3	Digital, EEPROM:
U801	19A705454P1	Voltage Detector, sim to Seiko S 8054ALO.
U802	19A702536P1	Linear positive voltage regulator; sim to LM2931AZ-5.
		----- CRYSTALS -----
Y701	19A702511G26	Quartz: 11.0592 MHz.
		----- MISCELLANEOUS -----
	19A702364P310	Machine screw, TORX Drive: No. M3-0.5 x 10.
	19B801570P2	Holder, connector.
	19A705662P1	Connector, Elastomeric.
	19A702364P304	Machine screw, TORX drive, Pan Head.
		FRONT CAP ASSEMBLY 19D902180G1
A5		LCD ASSEMBLY 19A70509G5
		----- LEDS -----
H1	19C851660P1	Crystal Display.
		----- MISCELLANEOUS -----
	19A703685P3	LCD Connector.
	19B801569P1	Diffuser.
	19C851719P2	Lens.
		LCD DRIVER BOARD 19C851720G1
		----- CAPACITORS -----
C1	19A702052P6	Ceramic: 1500 pF ±10%, 50 VDCW.
C2	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW.
		----- DIODES -----
D1 thru D4	19A705713P1	LED, subminiature.
		----- JACKS -----
J2		Part of printed wire board.
		----- PLUGS -----
P1	19B801235P13	Terminal strip.
P2	19B801235P3	Terminal strip.
		----- TRANSISTORS -----
Q1	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
Q2	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.

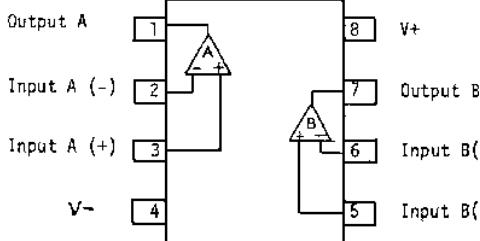
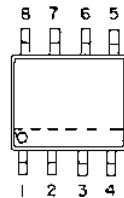
SYMBOL	PART NO.	DESCRIPTION
		----- RESISTORS -----
R1	19B801251P105	Metal film: 1M ohms ±5%, 1/10 w.
R2	19B801251P221	Metal film: 220 ohms ±5%, 1/10 w.
R3 and R4	19B801251P124	Metal film: 120K ohms ±5%, 1/10 w.
R5 and R6	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.
R7	19B801251P221	Metal film: 220 ohms ±5%, 1/10 w.
		----- INTEGRATED CIRCUITS -----
U1	19A705714P1	LCD Driver.
A6		CONTROL ASSEMBLY 19A70509G8
		----- CAPACITORS -----
C3 thru C7	19A702052P3	Ceramic: 470 pF ±10%, 50 VDCW.
		----- JACKS -----
J1	19A115834P1	Contact, electrical: sim to AMP 2-330808-8.
		----- MICROPHONES -----
M1	19A701301P3	Cartridge: Electret.
		----- SWITCHES -----
S1	19A705712P1	Switch, subminiature.
S2	19A705712P2	Switch, subminiature.
		----- MISCELLANEOUS -----
	19A705733P3	Control frame, circuitized.
	19B801571P3	Dome switch.
	19C851722P1	Boot, auxiliary jack.
		----- MODULE -----
B902	19A149673P1	Round: Water Proof, 24 ohms, 1/2 w.; sim to Line Electric Co. VS-50W24.
		----- MISCELLANEOUS -----
	19A149926P2	Insulator.
	19A702364P304	Machine screw, TORX drive, Pan Head.
	19C851997P1	Gasket, Speaker.
	19C851636P1	Switch pad.
	19A149926P4	Insulator.
	19D901978P5	Cap Assembly, Includes:
	19A116318P4	Front cover.
	19A705664P1	Foil, Magnetic Shielding: 1.50 inches wide.
		Gasket.

PRODUCTION CHANGES		
Changes in the equipment to improve performance or to simplify circuits are identified by a "Revision Letter", which is stamped after the model number of the unit. The revision stamped on the unit includes all previous revisions. Refer to the Parts List for the descriptions of parts affected by these revisions.		
REV. A - AUDIO/LOGIC BOARD 19D902142G3 & G4 To improve data integrity in the personality PROM due to power switching on/off added C807, deleted Q705, R713, and R714, and changed U701. Old part numbers were:		
Q705 - 19A700059P2, Silicon, PNP. R713 - 19B801251P223, Metal film: 22K ohm ±5%, 1/10 w. R714 - 19B801251P222, Metal film: 2.2K ohm ±5%, 1/10 w. U701 - 19A704724P1, EEPROM, 512 × 8 serial; sim to Xicor X2404.		
F R O N T		
REV. B - AUDIO/LOGIC BOARD 19D902142G3 & G4 No Changes.		
REV. C - AUDIO/LOGIC BOARD 19D902142G3 & G4 To incorporate the use of a new VCO module changed R321. Old part number was:		
R321 - 19A705496P6, Variable: 50K ohms.		
REV. A - MICROPROCESSOR/SPUR FILTER BOARD 19C851678G1 & G2 To add Channel Guard disable capability and update digital Channel Guard squelch tail elimination software changed U1. Old part numbers were:		
U1 - 19A704345P2, Microcomputer: CMOS, 8 bit; sim to N80C51BH. (Used in G1). U1 - 19A704345P3, Microcomputer: CMOS, 8 bit; sim to N80C51BH. (Used in G2).		
A S S E B L Y		
REV. B - MICROPROCESSOR/SPUR FILTER BOARD 19C851678G1 & G2 To make more parts common between the different groups changed R2 and R3 in G1, and added R2 and R3 to G2. Old part numbers were:		
R2 - 19B801251P102, Metal film: 1K ohm ±5%, 1/10 w. R3 - 19B801251P1		

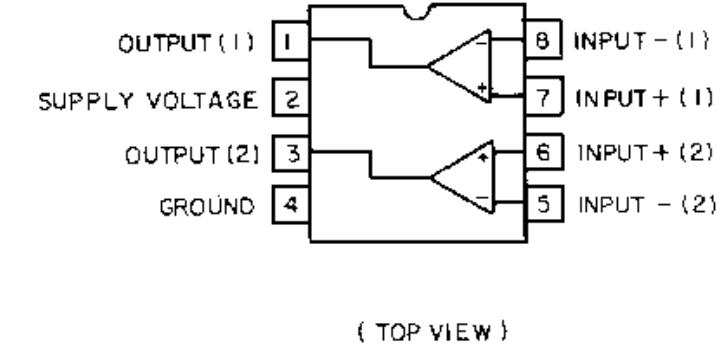
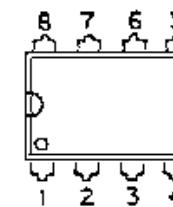
LCD DRIVER U1
19A705714P1



OPERATIONAL AMPLIFIER
U302/U703/U602
19A702293P2

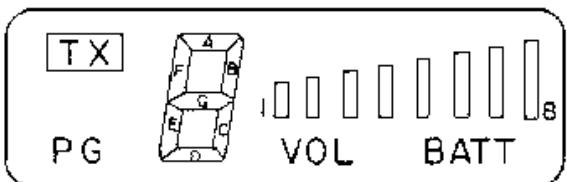


AUDIO AMPLIFIER U604
19A705452P1



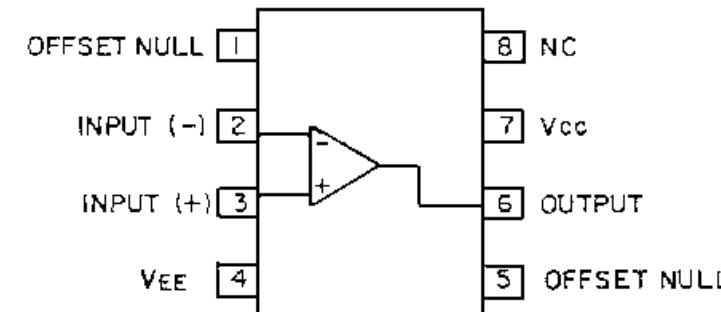
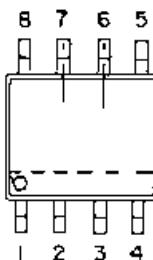
(TOP VIEW)

LCD
19C851660P1

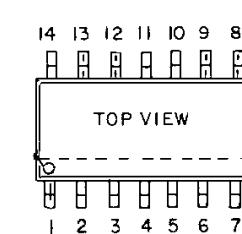


PIN	OUT
1	COM
2	PG
3	I _E
4	I _D
5	I _C
6	BAR 1
7	BAR 2
8	VOL
9	BAR 5
10	BAT
11	—
12	COM
13	—
14	BAR 8
15	BAR 7
16	BAR 6
17	BAR 4
18	BAR 3
19	BAR 2
20	I _A
21	I _F
22	I _G
23	TX
24	COM

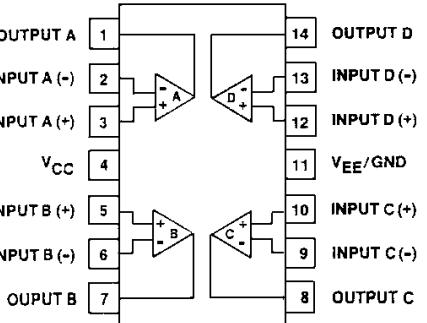
OPERATIONAL AMPLIFIER U301
19A705450P3

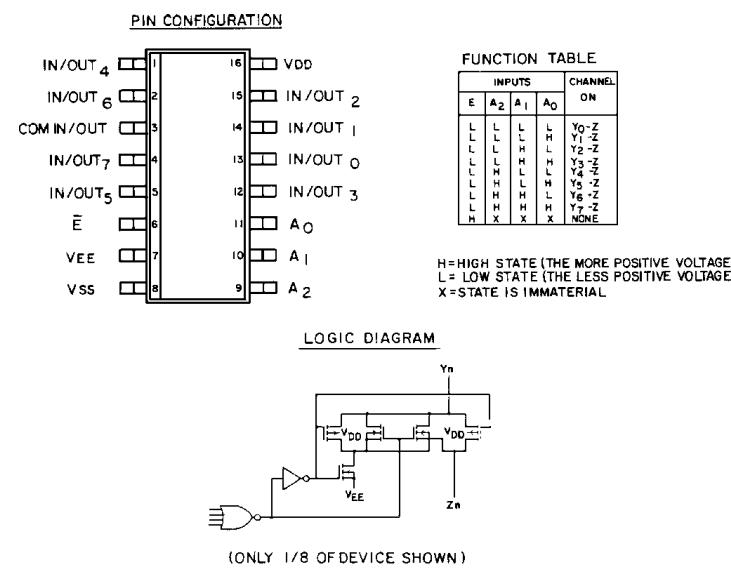
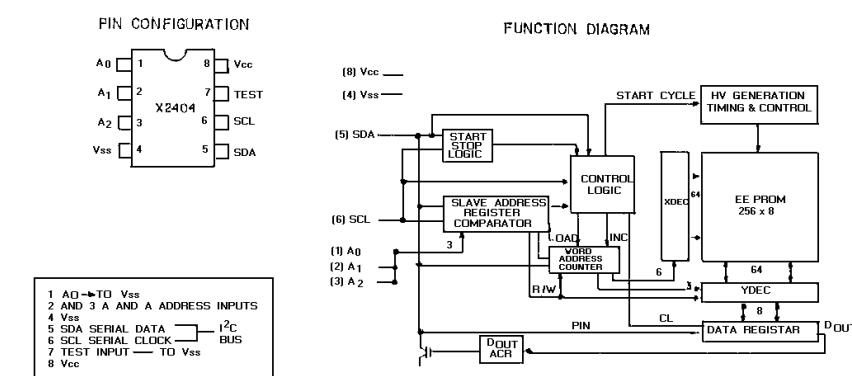
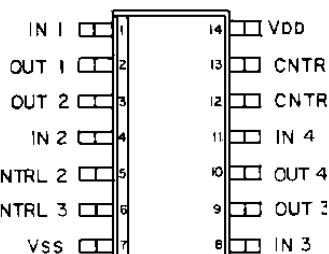
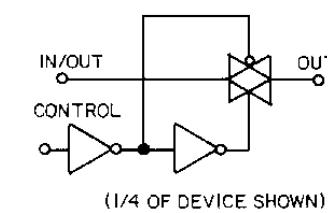


OPERATIONAL AMPLIFIER U601
19A702293P1



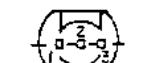
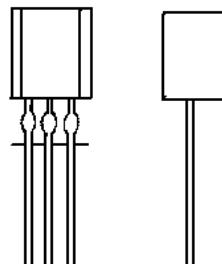
PIN 1 MAY BE IDENTIFIED BY INDENT OR CHAMFER

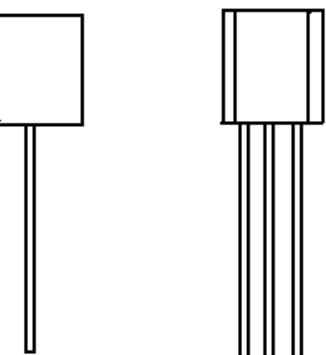


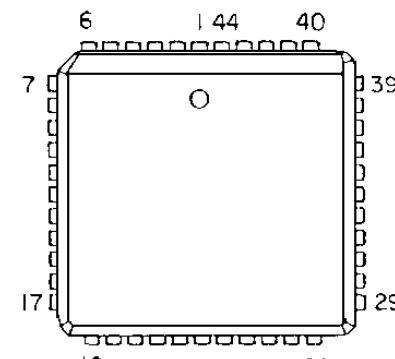
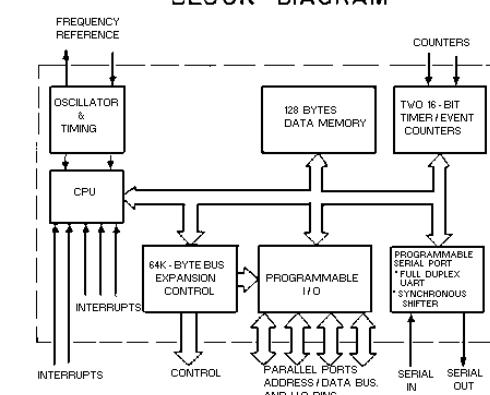
BILATERAL SWITCH U603
19A702705P3

EPROM U701
19A70474P1

BILATERAL SWITCH U605
19A702705P1
PIN CONFIGURATIONLOGIC DIAGRAM

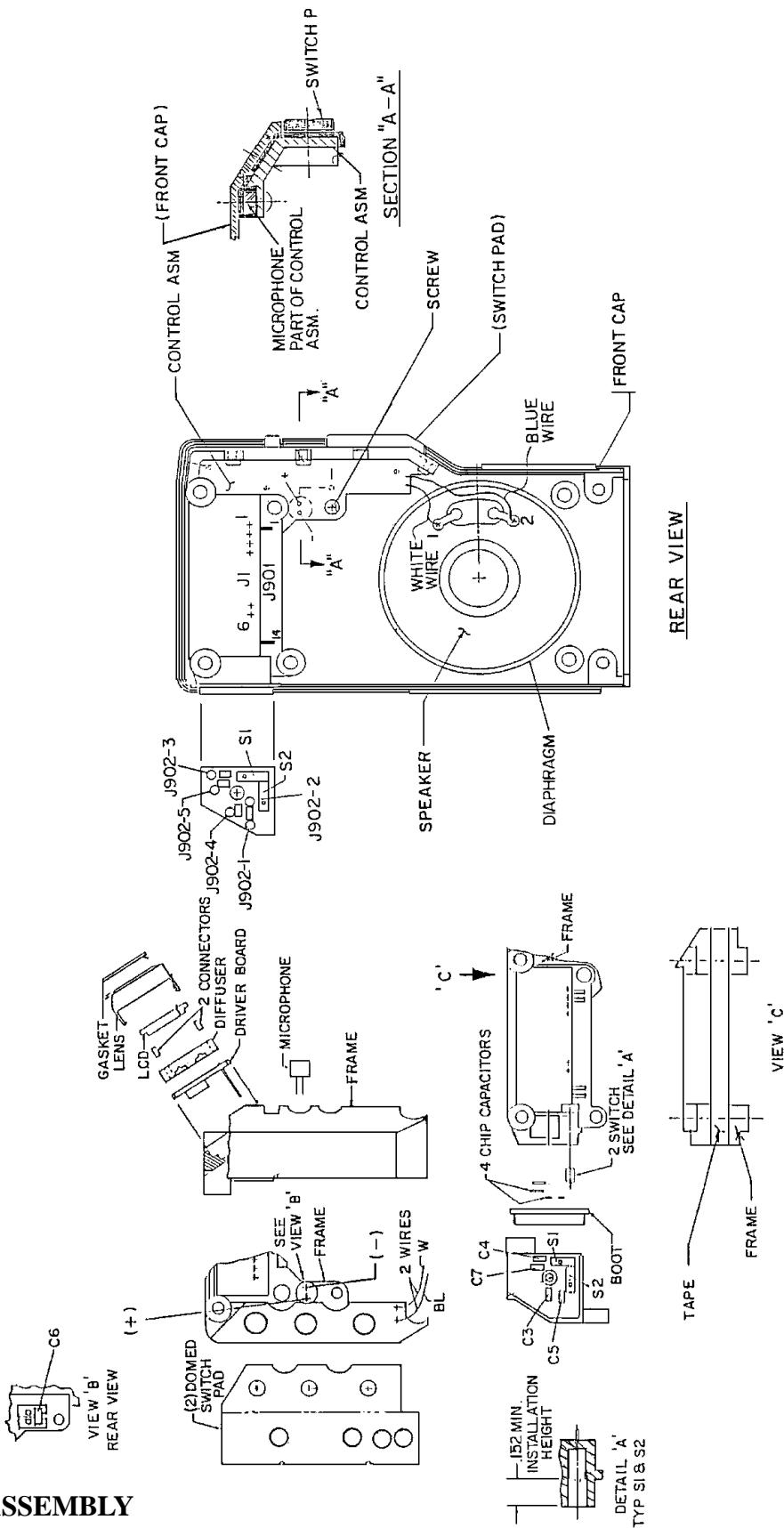
CONTROL	SWITCH
0	OFF
1	ON

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A
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VOLTAGE, DETECTOR U801
19A705454P1
BOTTOM VIEW
TO 92 PACKAGE
PIN 1 - OUT
PIN 2 - VDD
PIN 3 - VSS

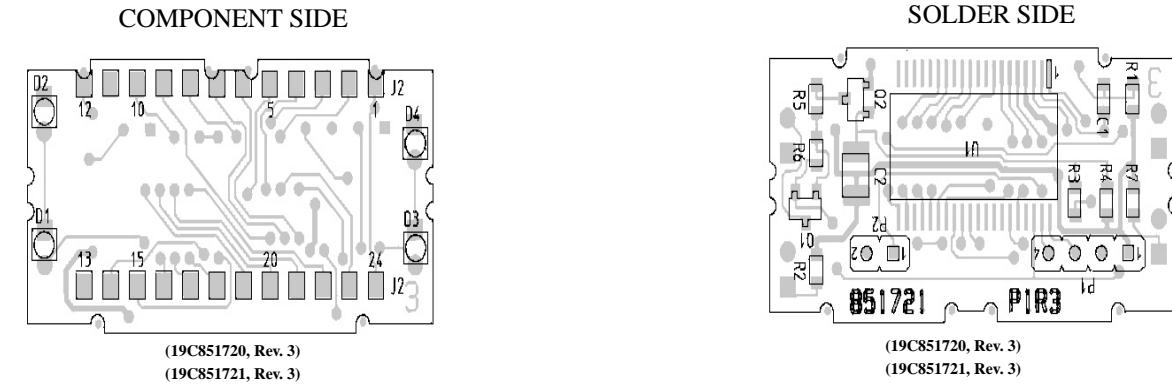
VOLTAGE REGULATOR U802
19A702536P1
BOTTOM VIEW
PIN 1 INPUT
PIN 2 OUTPUT
PIN 3 GROUND

MICROPROCESSOR U1 (80C51)
19A704345P2 & P3
BLOCK DIAGRAM

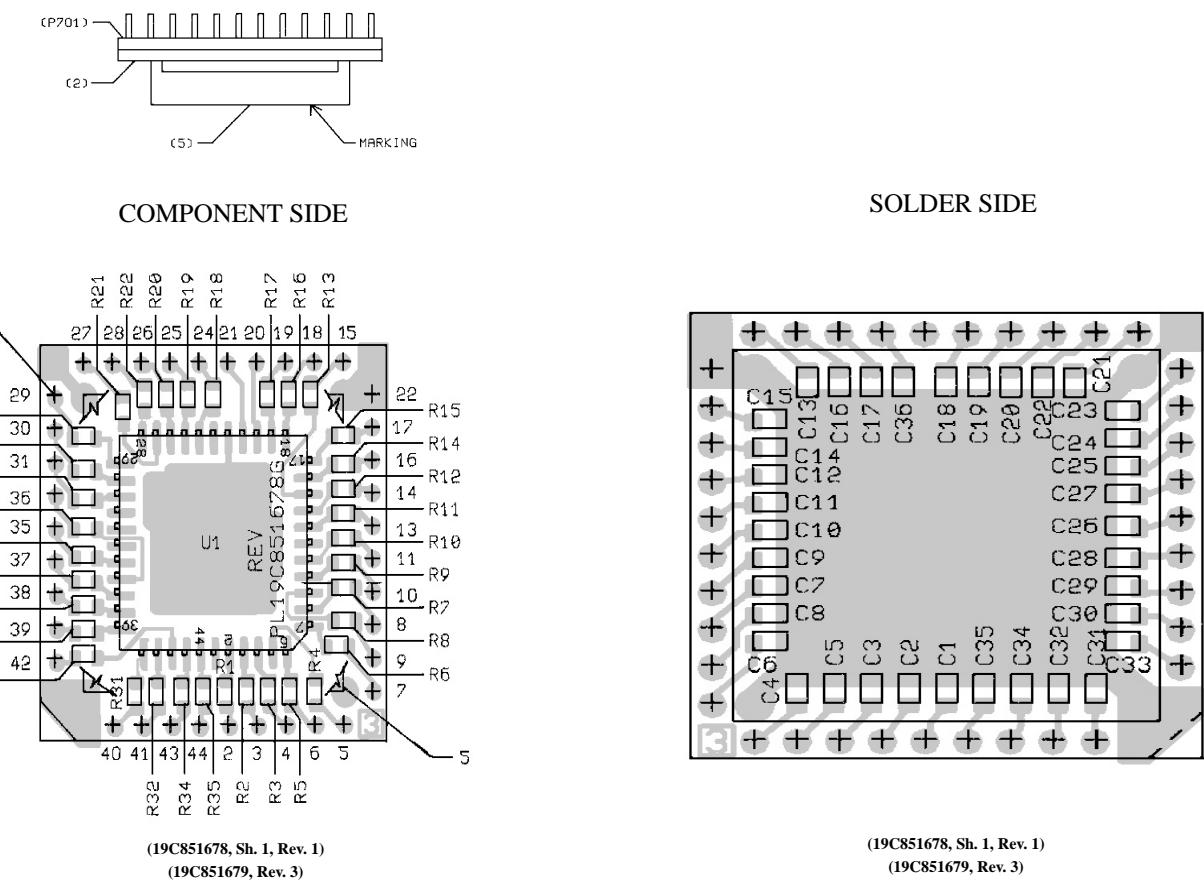
**FRONT CAP ASSEMBLY**

19D902180G1

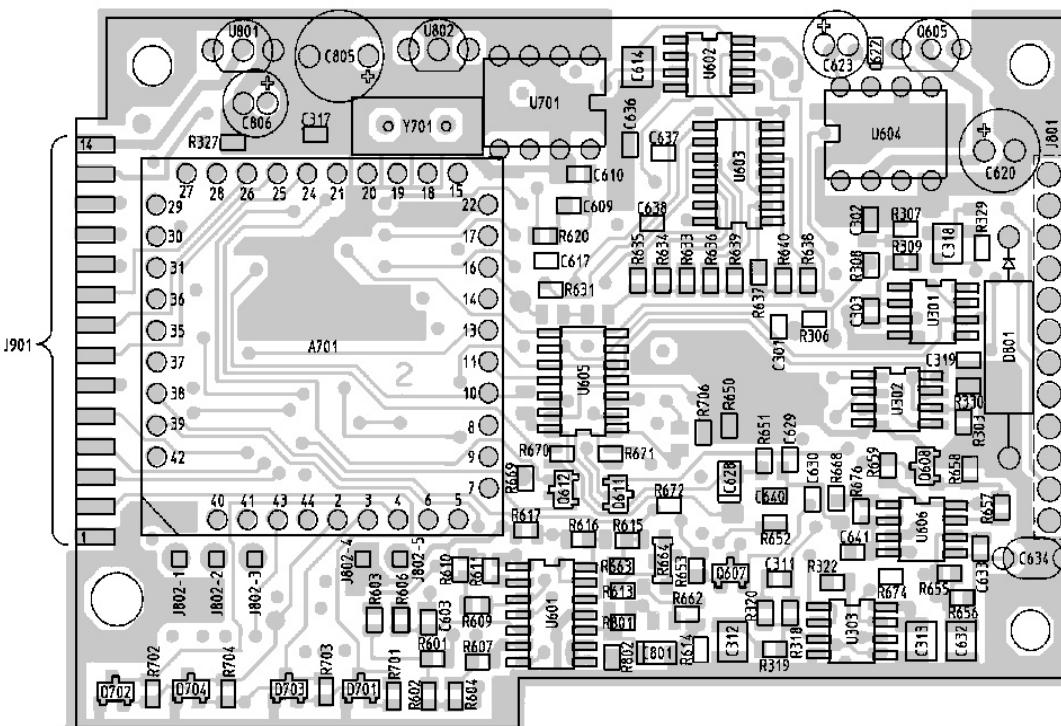
LCD BOARD
19C851720G1



SPUR FILTER BOARD
19C851678G1 & G2



COMPONENT SIDE



(19D902142, Sh. 2, Rev. 4)
(19D902141, First Layer, Rev. 2)

**LEAD IDENTIFICATION FOR
D601 & D701-D707
(SOT) DIODES
(TOP VIEW)**



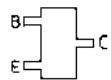
LEAD IDENTIFICATION
FOR U801

FLAT

IN-LINE
TOP VIEW

NOTE: CASE SHAPE IS DETERMINING
FACTOR FOR LEAD IDENTIFICATION

LEAD IDENTIFICATION FOR
Q601-0608, Q701, Q702, Q704-Q706
Q801-Q803
(SOT) TRANSISTORS



LEAD IDENTIFICATION
FOR Q605

FLAT

A B C

IN-LINE
TOP VIEW

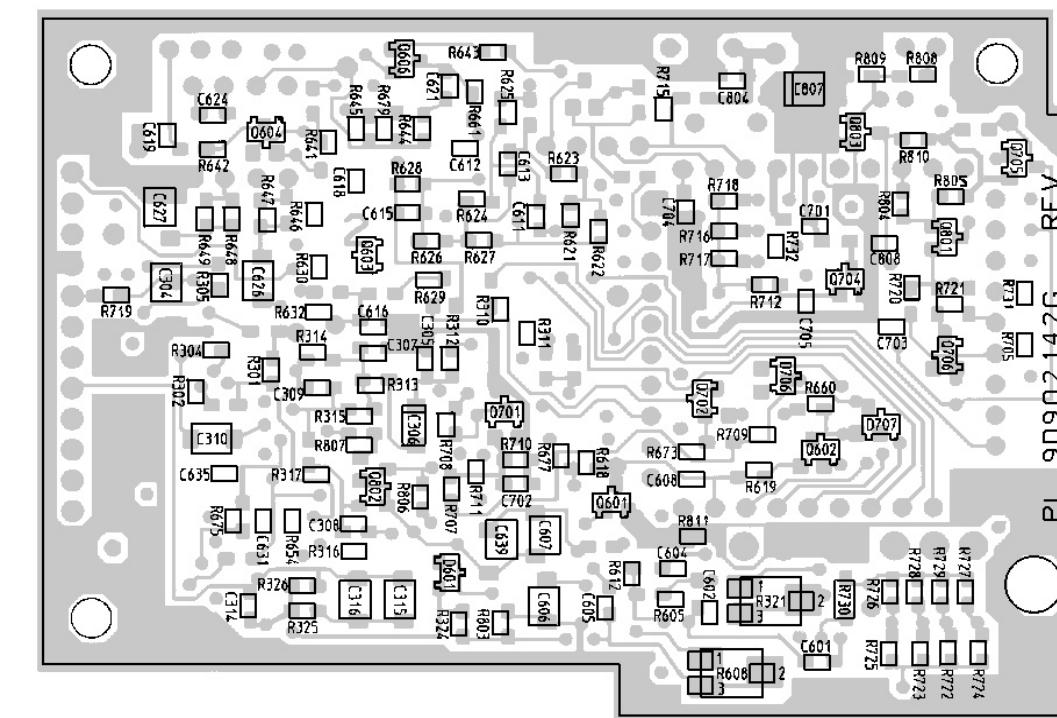
NOTE: CASE SHAPE IS DETERMINING
FACTOR FOR LEAD IDENTIFICATION

LEAD IDENTIFICATION
 FOR U802
 FLAT

 IN-LINE
 TOP VIEW
 NOTE: CASE SHAPE IS DETERMINING

NOTE: CASE SHAPE IS DETERMINING
FACTOR FOR LEAD IDENTIFICATION

SOLDER SIDE

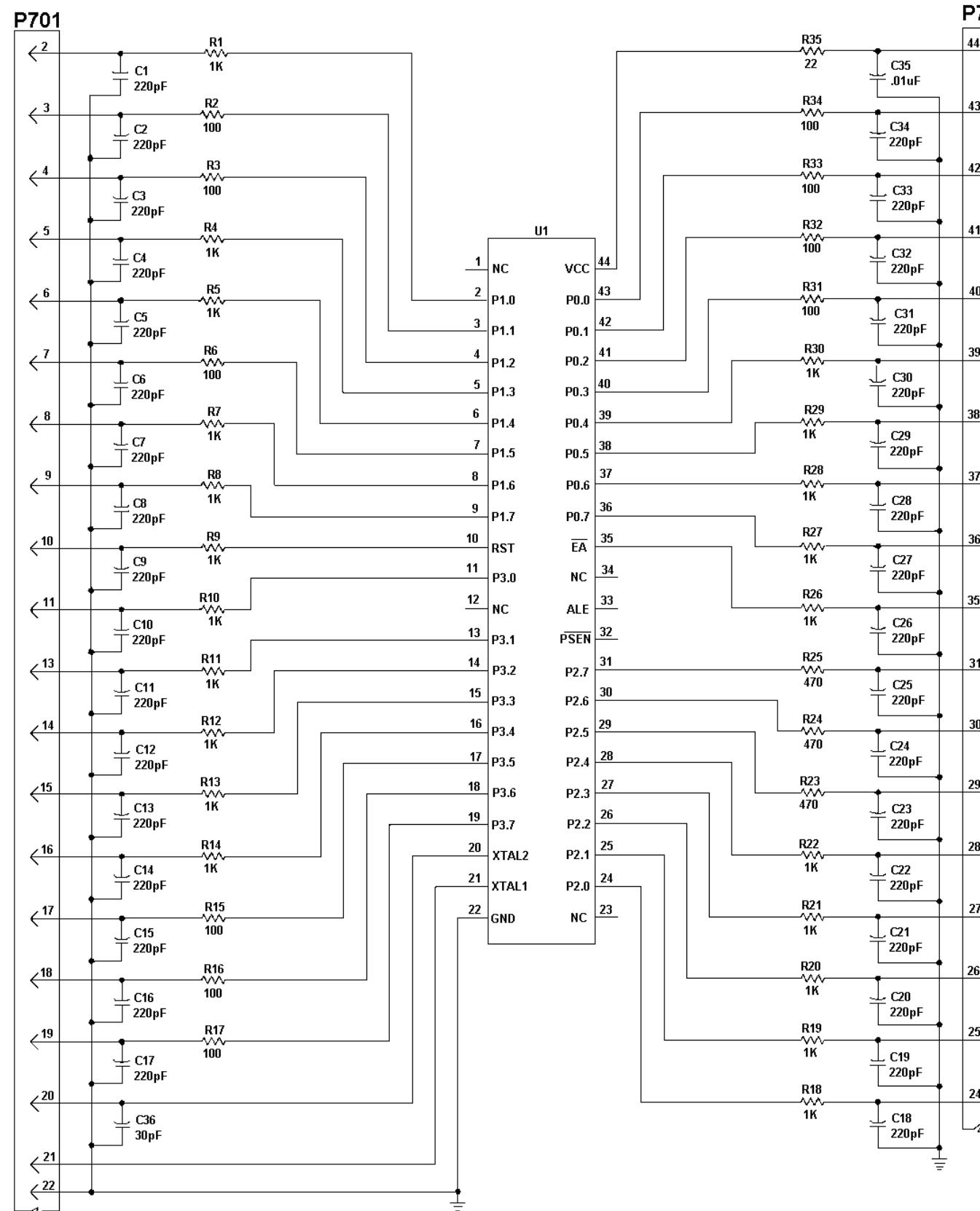


(19D902142, Sh. 2, Rev. 4)
(19D902141, Fourth Layer, Rev. 2)

F R O N T A S S E M B L Y

AUDIO/LOGIC BOARD

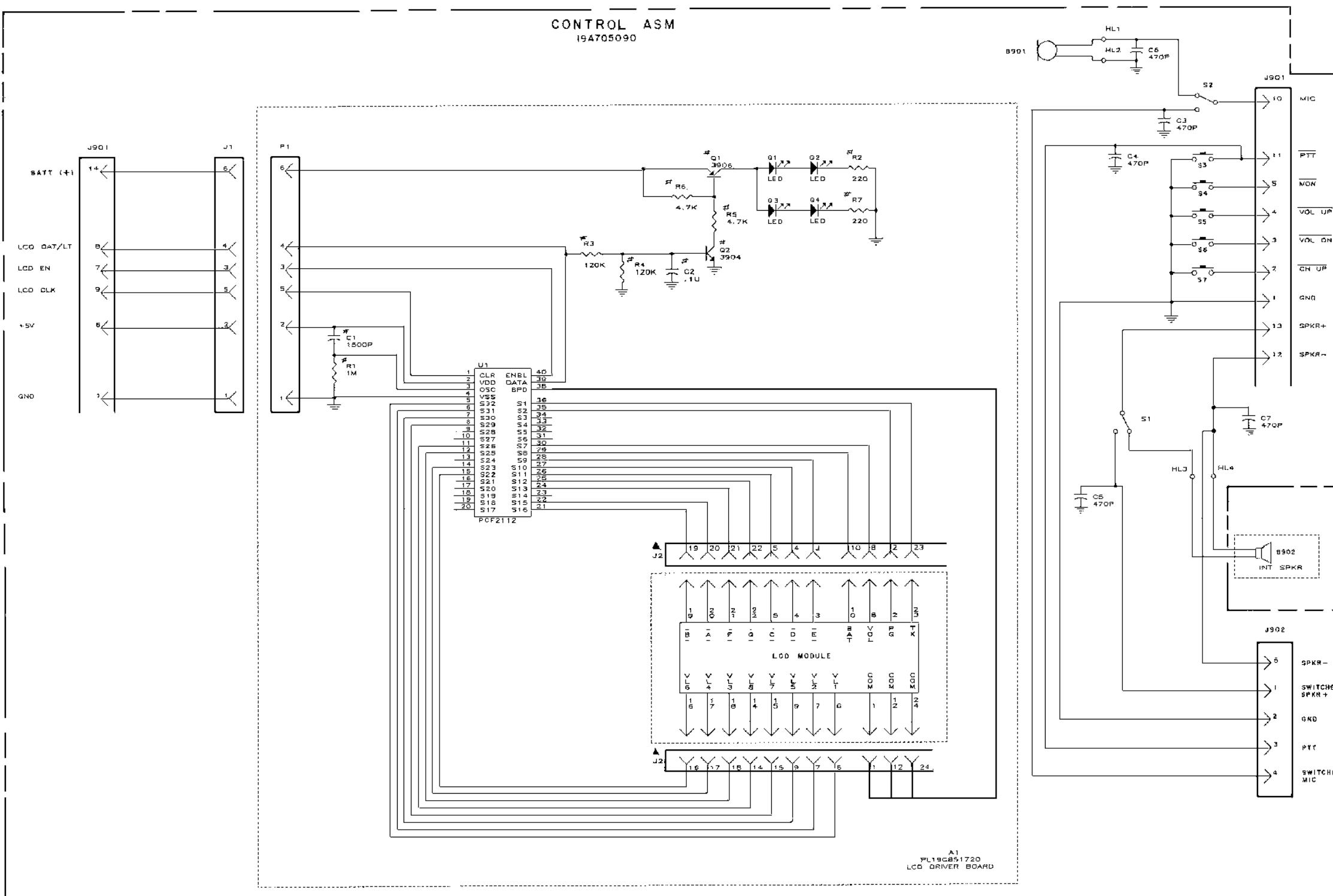
19D902142G3, G4



SPUR FILTER BOARD
19C851678G1 & G2

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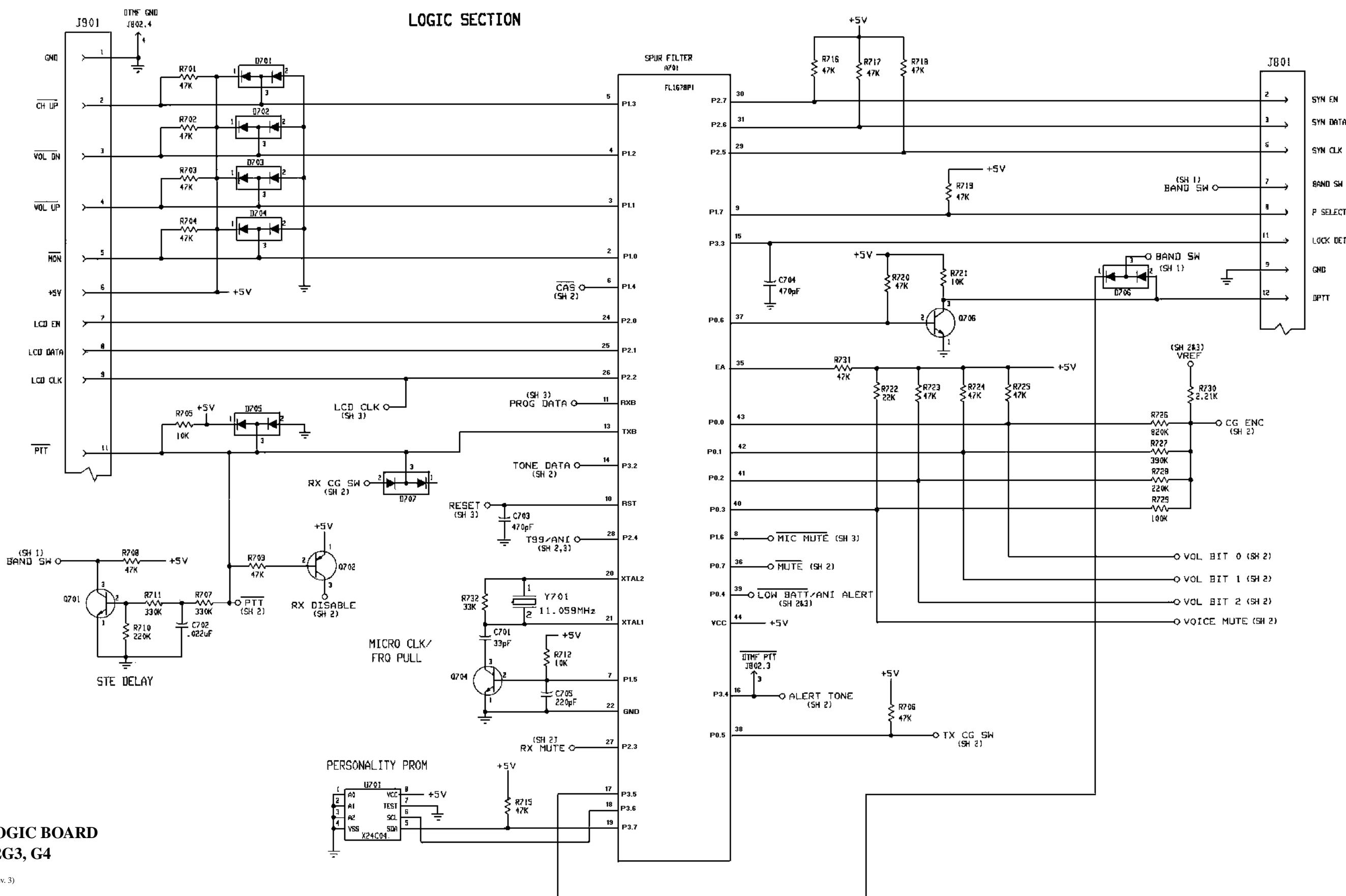
NOTES:

1. ALL RESISTORS ARE .1 WATT UNLESS OTHERWISE SPECIFIED.
RESISTOR VALUES IN Ω UNLESS FOLLOWED BY MULTIPLIER K OR M.
CAPACITOR VALUES IN F UNLESS FOLLOWED BY MULTIPLIER U,N OR P.
INDUCTANCE VALUES IN H UNLESS FOLLOWED BY MULTIPLIER M OR U.
2. # INDICATES CHIP COMPONENTS.
3. ▲ PART OF PWB.

FRONT CAP ASSEMBLY
19D902180G1

(19D902216, Sh. 1, Rev. 3)

LOGIC SECTION



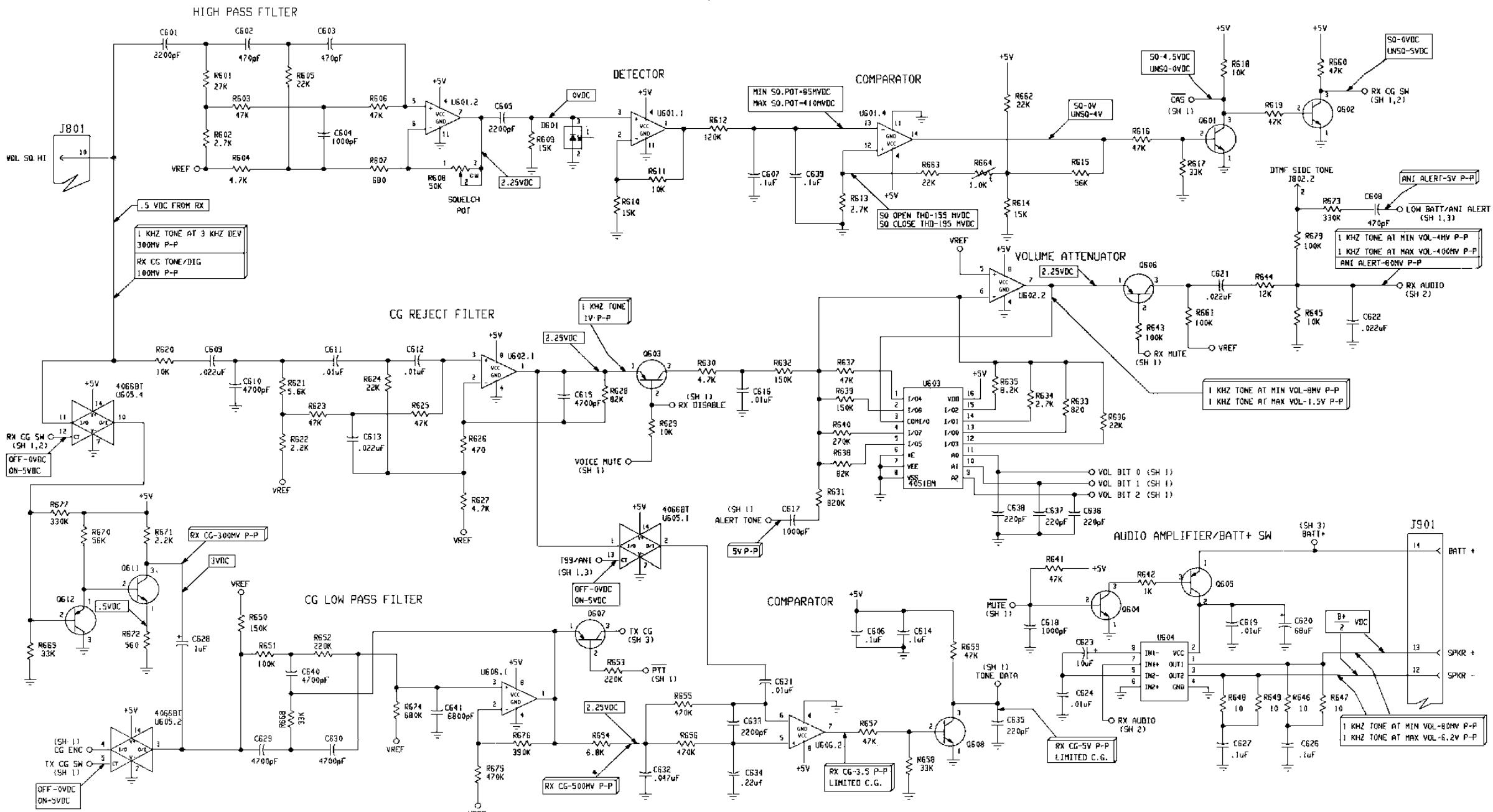
AUDIO/LOGIC BOARD
19D902142G3, G4

(19D902586, Sh. 1, Rev. 3)

F
R
O
N
T

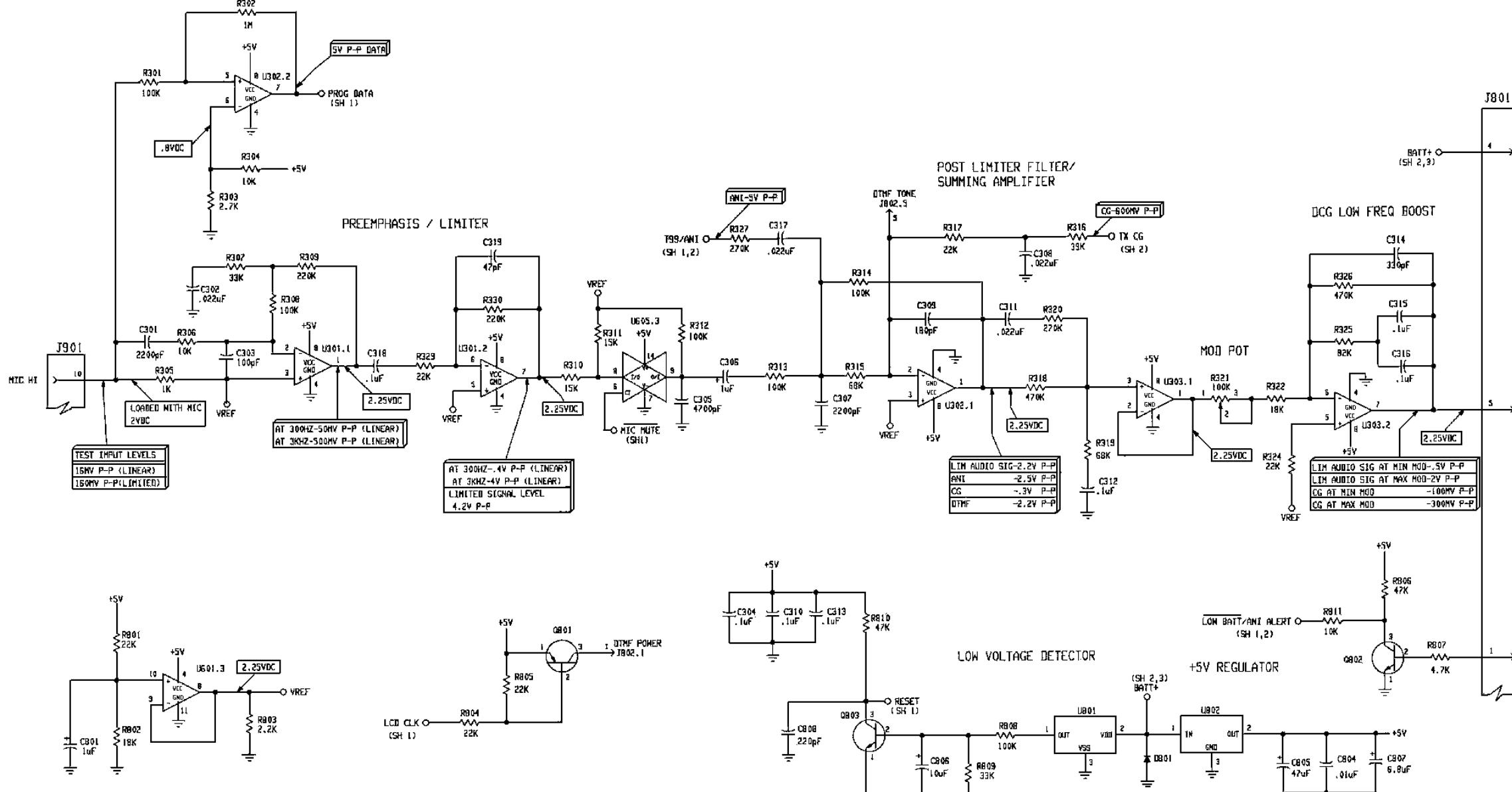
A
S
S
E
M
B
L
Y

RX AUDIO SECTION



AUDIO/LOGIC BOARD
19D902142G3 AND G4

TX AUDIO/POWER SUPPLY SECTION



ALL RESISTORS ARE 0.1 WATT UNLESS OTHERWISE SPECIFIED AND RESISTORS VALUES ARE IN OHMS UNLESS FOLLOWED BY MULTIPLIER K OR M.
CAPACITOR VALUES IN F UNLESS FOLLOWED BY MULTIPLIER U, N OR P.
INDUCTANCE VALUES IN H UNLESS FOLLOWED BY MULTIPLIER M OR U

LBI SCHEMATIC DRAWING REF ID: 19
MODEL NO. 19D902142G3 REV LETTER E
19D902142G4 E

AUDIO/LOGIC BOARD
19D902142G3 AND G4

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